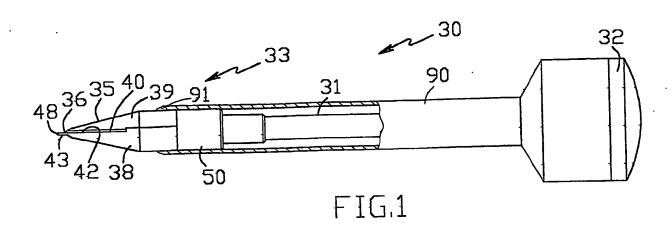
1/10



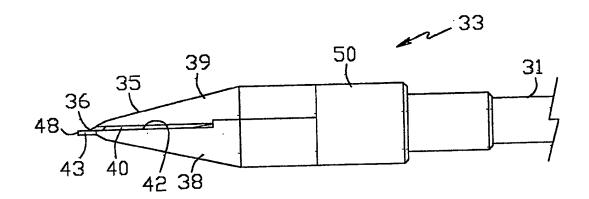


FIG.2

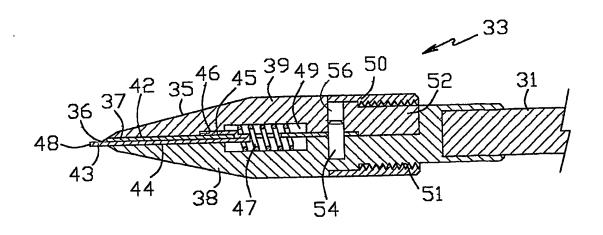
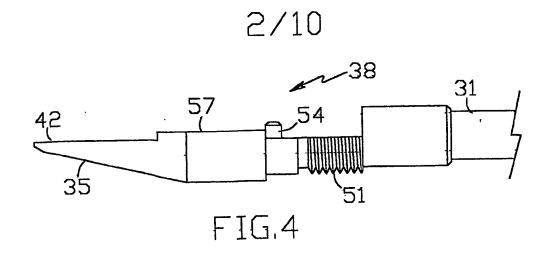


FIG.3

WO 2004/112564 PCT/IL2004/000554



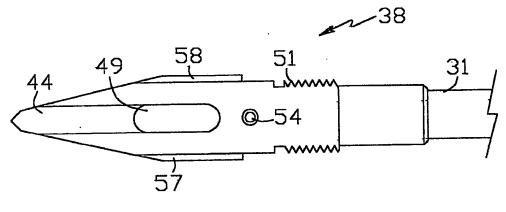


FIG.5

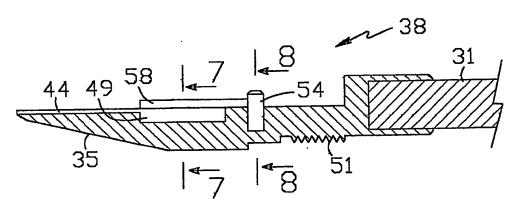
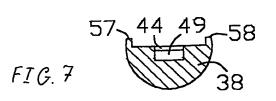
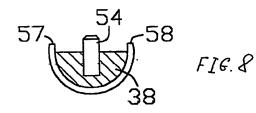
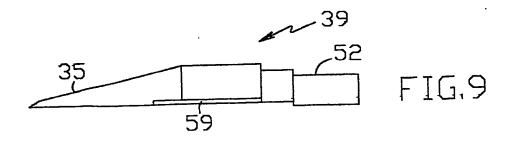


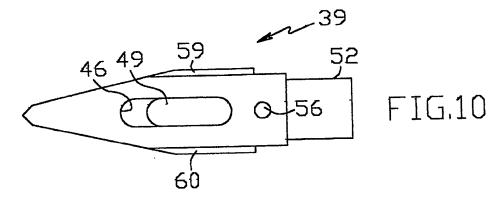
FIG.6

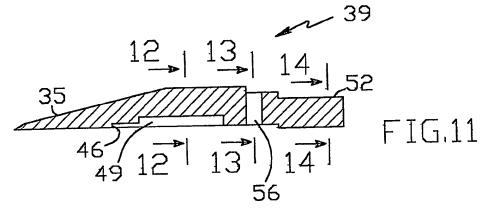


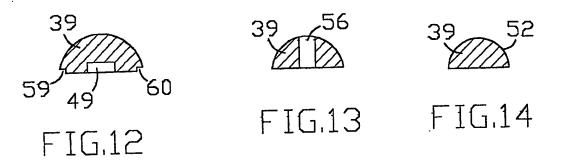


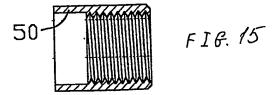
3/10

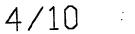


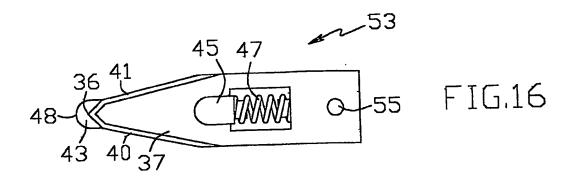


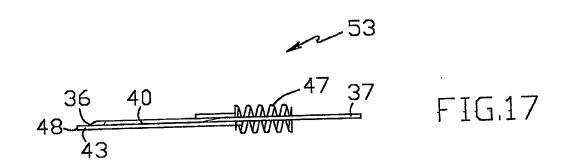












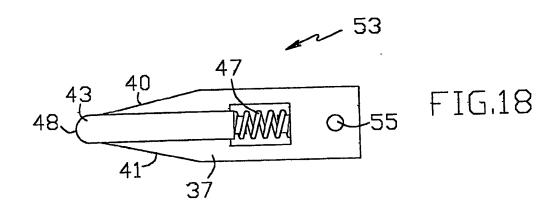
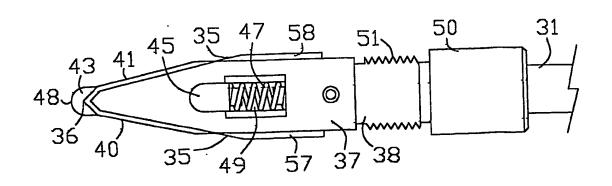
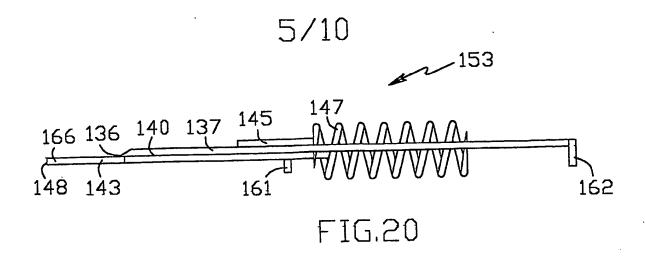
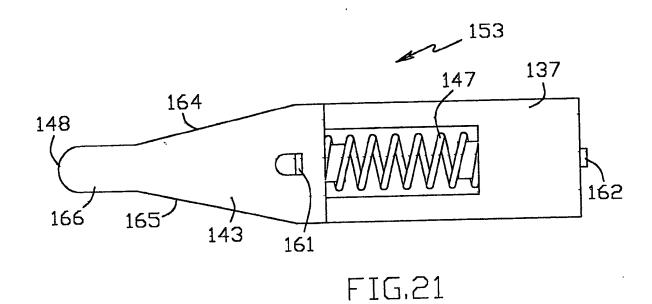
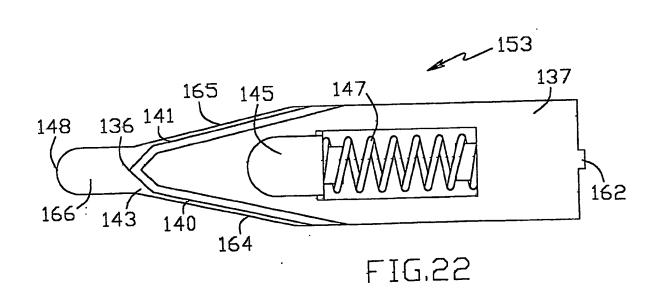


FIG. 19









6/10

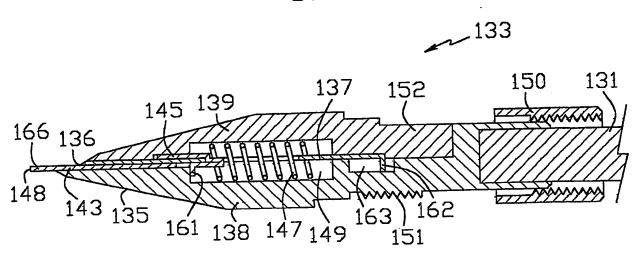


FIG.23

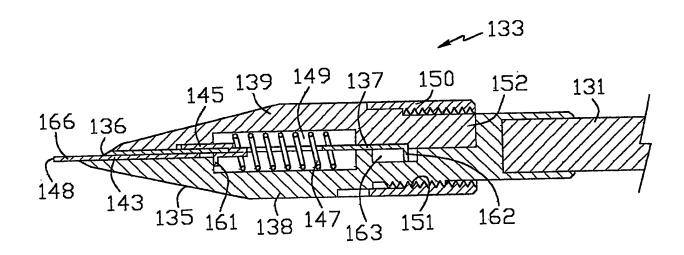


FIG.24

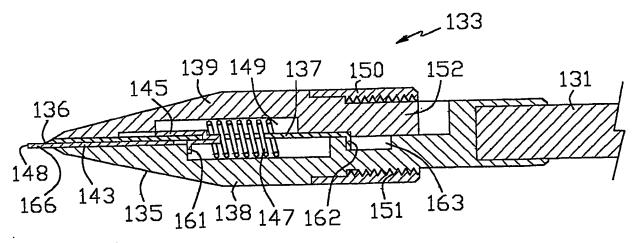


FIG. 25

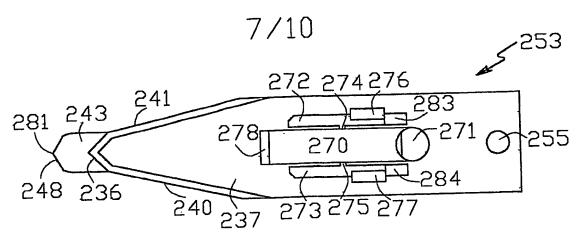


Fig.26

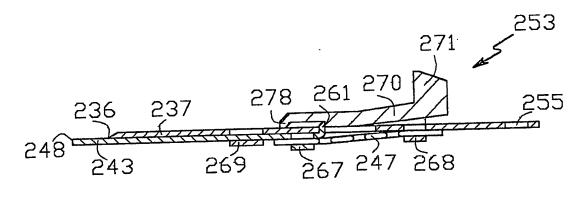
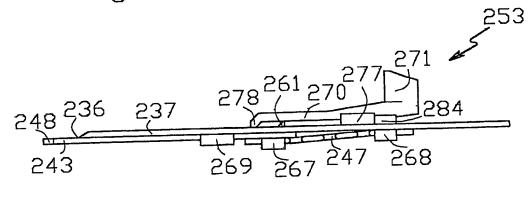


Fig.27



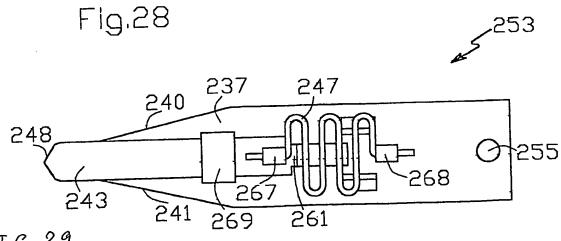


FIG. 29

PCT/IL2004/000554

